



# WF04P ±1%, ±5% High Power Chip Resistors Size 0402, 1/8W

\*Contents in this sheet are subject to change without prior notice.



## FEATURE

- 1. High Power and stability
- 2. Reduced size of final equipment
- 3. Lower assembly costs
- 4. Higher component and equipment reliability
- 5. RoHS compliant and Lead free products

## APPLICATION

- Consumer electrical equipment
- Automotive application
- EDP, Computer application
- Telecom application

# DESCRIPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer.

The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (lead free) alloy.

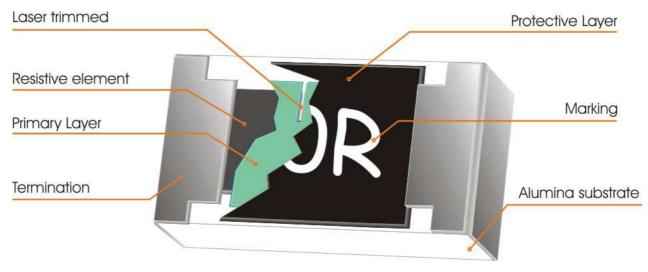


Fig 1. Consctruction of a Chip-R

# QUICK REFERENCE DATA

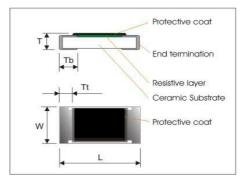
Item	General Specification		
Series No.	WF04P		
Size code	0402 (	1005)	
Resistance Range	1Ω~1MΩ (±5%,	±1%), Jumper	
Resistance Tolerance	±1% E96/E24	±5% E24	
TCR (ppm/°C)			
R = 1MΩ	≤±200	≤ ± 200	
10Ω < R < 1MΩ	≤±100	≤ ± 200	
$R \leq 10\Omega$	≤ <b>-200</b> ~ <b>+</b> 400	≤ <b>-200</b> ~ <b>+400</b>	
Max. dissipation @ T <sub>amb</sub> =70°C	1/8 W		
Max. Operation Voltage (DC or RMS)	50V		
Max. Overload Voltage (DC or RMS)	100V		
Climatic category	55/155/56		

Note :

- 1. This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2. Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by
- 3. RCWV =  $\sqrt{\text{RatedPower} \times \text{Resistance Value}}$  or Max. RCWV listed above, whichever is lower.
- 4. The resistance of Jumper is defined  $<0.05\Omega$ .

#### **DIMENSIONS** (unit : mm)

	WF04P		
L	$1.00 \pm 0.05$		
w	$0.50\pm0.05$		
Т	$0.35\pm0.05$		
Tb	0.25 ± 0.10		
Tt	0.20 ± 0.10		





## MARKING

No marking for WF04P

# FUNCTIONAL DESCRIPTION

#### Product characterization

Standard values of nominal resistance are taken from the E24 series for resistors with a tolerance of  $\pm$ 5%, and E96 series for resistors with a tolerance of  $\pm$ 1%. The values of the E24/E96 series are in accordance with "IEC publication 60063"

#### Derating

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

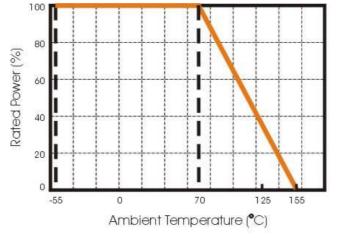


Figure 2 Maximum dissipation in percentage of rated power as a function of the ambient temperature for WR04X

# MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



## **SOLDERING CONDITION**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 245°C during 3 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

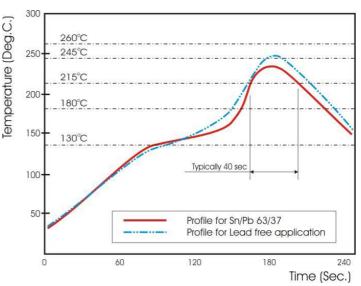


Fig 3. Infrared soldering profile for Chip Resistors

## **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with .

WF04	Р	472_	J	т	L
WF04 Size code WF04 : 0402	P Type code P : 0402 1/8W	472_Resistance code $\pm 5\%$ , E24: 2 significant digits followed by no. of zeros and a blank $4.7\Omega$ $=4R7$ $10\Omega$ $=100$ $220\Omega$ $=221$ Jumper $=000$ ("" means a blank)	J Tolerance F : ±1% J : ±5% P : Jumper	TPackaging codeT: 7" Reeled tapingQ: 10" Reeled tapingG: 13" Reeled tapingB: Bulk	L Termination code L = Sn base (lead free)
		$\pm$ 1%, E96: 3 significant digits followed by no. of zeros 102Ω =1020 37.4KΩ =3742			

1. Reeled tape packaging : 8mm width paper taping 10000pcs per 7" reel.

2. Bulk packaging : 10,000pcs per poly-bag

### TEST AND REQUIREMENTS(JIS C 5201-1 : 1998)

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range : Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS.

The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied :

Temperature: 15°C to 35°C.

Relative humidity: 45% to 75%.

Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar).

All soldering tests are performed with midly activated flux.

DC resistanceDC resistance values measured at the test voltages specified below : <100@0.1V, <1000@0.3V, <1K0@1.0V, <10K0@30V	TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
Clause 4.5specified below : <1000 $(20.3V)$ , <1K0 $(21.0V)$ , <10K0 $(23.V)$ , <100K0 $(20.3V)$ , <1K0 $(21.0V)$ , <10K0 $(23.V)$ , <100K0 $(23.V)$ , <100K0 $(23.V)$ , <1K0 $(21.0V)$ , <10K0 $(23.V)$ , <100K0 $(23.V)$ , <1K0 $(21.0V)$ , <10K0 $(23.V)$ , <100K0 $(23.V)$ , <1K0 $(21.0V)$ , <10K0 $(23.V)$ , <100K0 $(23.V)$ , <1K0 $(23.V)$ , <10K0 $(23.V)$ , <10K0 $(23.V)$ , <1K0 $(23.V)$ , <10K0 $(23.V)$ , <br< th=""><th>TEST</th><th>PROCEDORE / TEST METHOD</th><th>Resistor</th><th>0Ω</th></br<>	TEST	PROCEDORE / TEST METHOD	Resistor	0Ω	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	DC resistance Clause 4.5				
		<10Ω@0.1V, <100Ω@0.3V, <1KΩ@1.0V,	Within the specified tolerance	<50m $\Omega$	
Resistance(T.C.R) Clause 4.8centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 (ppm/°C) t_1 : 20°C+5°C-1°CR_1 : Resistance at reference temperatureR_2 : Resistance at reference temperatureR_2 : Resistance at test temperatureRefer to"QUICK REFERENCE DATA"N/aShort time overload(S.T.O.L)Permanent resistance change after a 5second applicationof a voltage specified in the above list, whichever is less.\Delta R/R \max. \pm (2\%+0.10\Omega)<50mΩ$					
$\begin{array}{c} \frac{1}{R_1(t_2-t_1)} \times 10^{\circ} \ (ppm/^{\circ}C) \ t_1: 20^{\circ}C+5^{\circ}C-1^{\circ}C \\ R_1(t_2-t_1) \\ R_1: Resistance at reference temperature \\ R_2: Resistance at test temperature \\ R_2: Resistance to soldering \\ reat(R_S.H) \\ Rec 60068-2-58:2004 \\ \end{tabular} \\ Un-mounted chips completely immersed for 10\pm1second \\ n a SAC solder bath at 255^{\circ}C\pm5^{\circ}C \\ \end{tabular} \\ tabular$	Temperature Coefficient of Resistance(T.C.R)				
R2 : Resistance at test temperatureARShort time overload (S.T.O.L)Permanent resistance change after a 5second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less. $\Delta R/R \max. \pm (2\%+0.10\Omega)$ <50mΩ	Clause 4.8	$\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}  t_1 : 20^{\circ} \text{C} + 5^{\circ} \text{C} - 1^{\circ} \text{C}$		N/a	
(S.T.O.L)of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less. $\Delta R/R \max. \pm (2\%+0.10\Omega)$ <50mΩClause 4.13Un-mounted chips completely immersed for 10±1second in a SAC solder bath at 255°C±5°C $\Delta R/R \max. \pm (1\%+0.05\Omega)$ no visible damage<50mΩ		·			
Data SeriesDefinition $\Delta R/R \max. \pm (1\%+0.05\Omega)$ no visible damage $<50m\Omega$ Sesistance to soldering reat(R.S.H)Un-mounted chips completely immersed for $3\pm 0.3$ second in a SAC solder bath at $255^\circ$ C $\pm 5^\circ$ C $\Delta R/R \max. \pm (1\%+0.05\Omega)$ no visible damage $<50m\Omega$ SolderabilityUn-mounted chips completely immersed for $3\pm 0.3$ second in a SAC solder bath at $245^\circ$ C $\pm 5^\circ$ C $95\%$ coverage min., good tinning and no visible damageTemperature cycling30 minutes at $-55^\circ$ C $\pm 3^\circ$ C, $2-3$ minutes at $20^\circ$ C $\pm 5^\circ$ C- $\Delta R/R \max. \pm (1\%+0.05\Omega)$ $<50m\Omega$ Clause 4.1930 minutes at $+155^\circ$ C $\pm 3^\circ$ C, $2-3$ minutes at $20^\circ$ C $\pm 5^\circ$ C- $\Delta R/R \max. \pm (1\%+0.05\Omega)$ $<50m\Omega$ Damp Heat1000 $+48/-0$ hours, loaded with RCWV or Vmax in humidity chamber controller at $40^\circ$ C $\pm 2^\circ$ C and $90-95\%$ relative humidity, 1.5hours on and 0.5 hours off $\Delta R/R \max. \pm (3\%+0.10\Omega)$ R<10 $\Omega_1$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ R<10 $\Omega_2$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ $<50m\Omega$ Load Life(Endurance) $1000 + 48/-0$ hours; loaded with RCWV or Vmax in chamber controller $70\pm 2^\circ$ C, 1.5 hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ R<10 $\Omega_2$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ R<10 $\Omega_2$ : $\Delta R/R \max. \pm (5\%+0.10\Omega)$ $<50m\Omega$ Bending strengthResistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for WR04 $\Delta R/R \max. \pm (1\%+0.05\Omega)$ $<50m\Omega$ $\Delta R/R \max. \pm (1\%+0.05\Omega)$ AdhesionPressurizing force: 5N, Test time: $10\pm 1sec$ .No remarkable damage or removal of	÷		ΔR/R max. ±(2%+0.10Ω)	<50mΩ	
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IEC 60068-2-58:2004in a SAC solder bath at $245^{\circ}C \pm 5^{\circ}C$ visible damageTemperature cycling Clause 4.1930 minutes at $-55^{\circ}C \pm 3^{\circ}C$ , $2-3$ minutes at $20^{\circ}C \pm 5^{\circ}C \pm 1^{\circ}C$ , $30$ minutes at $\pm 155^{\circ}C \pm 3^{\circ}C$ , $2-3$ minutes at $20^{\circ}C \pm 5^{\circ}C \pm 1^{\circ}C$ , $1^{\circ}C$ , total 5 continuous cycles $\Delta R/R \max. \pm (1\% + 0.05\Omega)$ <50m $\Omega$ Damp Heat (Load life in humidity) Clause 4.241000 + 48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at $40^{\circ}C \pm 2^{\circ}C$ and $90-95^{\circ}$ relative humidity, 1.5hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\% + 0.10\Omega)$ $R<10\Omega;:$ $\Delta R/R \max. \pm (5\% + 0.10\Omega)$ <50m $\Omega$ Load Life(Endurance) Clause 4.251000 + 48/-0 hours; loaded with RCWV or Vmax in chamber controller 70 \pm 2^{\circ}C, 1.5 hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\% + 0.10\Omega)$ $R<10\Omega;:$ $\Delta R/R \max. \pm (5\% + 0.10\Omega)$ <50m $\Omega$ Bending strength Clause 4.33Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for WR04No visual damaged, $\Delta R/R \max. \pm (1\% + 0.05\Omega)$ <50m $\Omega$ AdhesionPressurizing force: 5N, Test time: $10\pm 1$ sec.No remarkable damage or removal of	Resistance to soldering heat(R.S.H) IEC 60068-2-58:2004			<50mΩ	
Temperature cycling Clause 4.1930 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +155°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 30 minutes at +155°C±3°C, 2~3 minutes at 20°C+5°C-1°C, 1°C, total 5 continuous cycles $\Delta R/R max. \pm (1\%+0.05\Omega)$ <50m $\Omega$ Damp Heat (Load life in humidity)1000 +48/-0 hours, loaded with RCWV or Vmax in humidity chamber controller at 40°C±2°C and 90~95% 	Solderability				
Clause 4.1930 minutes at $\pm 155^{\circ}C\pm 3^{\circ}C$ , $2\sim 3$ minutes at $20^{\circ}C\pm 5^{\circ}C$ - $1^{\circ}C$ , total 5 continuous cycles $\Delta R/R \max. \pm (1\%\pm 0.05\Omega)$ $<50m\Omega$ Damp Heat1000 $\pm 48/-0$ hours, loaded with RCWV or Vmax in humidity chamber controller at $40^{\circ}C\pm 2^{\circ}C$ and $90\sim 95\%$ relative humidity, 1.5hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\%\pm 0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R \max. \pm (5\%\pm 0.10\Omega)$ $<50m\Omega$ Load Life(Endurance) $1000 \pm 48/-0$ hours; loaded with RCWV or V <sub>max</sub> in chamber controller $70\pm 2^{\circ}C$ , 1.5 hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\%\pm 0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R \max. \pm (5\%\pm 0.10\Omega)$ $<50m\Omega$ Bending strengthResistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for WR04No visual damaged, $\Delta R/R \max. \pm (1\%\pm 0.05\Omega)$ $<50m\Omega$ AdhesionPressurizing force: 5N, Test time: $10\pm 1$ sec.No remarkable damage or removal of $<100 \pm 100$					
Load life in humidity) Clause 4.24humidity chamber controller at $40^{\circ}C\pm 2^{\circ}C$ and $90-95\%$ relative humidity, 1.5hours on and 0.5 hours off $\Delta R/R \max. \pm (3\%+0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R \max. \pm (5\%+0.10\Omega)$ <50m $\Omega$ Load Life(Endurance) Clause 4.25 $1000 + 48/-0$ hours; loaded with RCWV or $V_{max}$ in chamber controller $70\pm 2^{\circ}C$ , 1.5 hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R \max. \pm (3\%+0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R \max. \pm (5\%+0.10\Omega)$ <50m $\Omega$ Bending strength Clause 4.33Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for WR04No visual damaged, $\Delta R/R \max. \pm (1\%+0.05\Omega)$ <50m $\Omega$ AdhesionPressurizing force: 5N, Test time: $10\pm 1$ sec.No remarkable damage or removal of the total back to the start	Temperature cycling Clause 4.19	30 minutes at +155°C±3°C, 2~3 minutes at 20℃+5℃-	$\Delta$ R/R max. ±(1%+0.05 $\Omega$ )	<50mΩ	
Clause 4.24Indimities in further of the form of the	Damp Heat	1000 +48/-0 hours, loaded with RCWV or Vmax in			
Clause 4.24relative humidity, 1.5hours on and 0.5 hours off $\Delta R/R \max. \pm (5\%+0.10\Omega)$ Load Life(Endurance)1000 +48/-0 hours; loaded with RCWV or V <sub>max</sub> in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off $10\Omega \sim 1M\Omega$ : $\Delta R/R \max. \pm (3\%+0.10\Omega)$ R<10 $\Omega,$ : 	(Load life in humidity)	humidity chamber controller at $40^{\circ}C\pm2^{\circ}C$ and $90\sim95\%$		<50m $\Omega$	
Load Life(Endurance)1000 +48/-0 hours; loaded with RCWV or V_max in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off $10\Omega ~ 1M\Omega$ : $\Delta R/R max. \pm(3\%+0.10\Omega)$ $R<10\Omega,:$ $\Delta R/R max. \pm(5\%+0.10\Omega)$ <50m $\Omega$ Bending strengthResistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 3mm for 10sec, 5mm for WR04No visual damaged, $\Delta R/R max. \pm(1\%+0.05\Omega)$ <50m $\Omega$ AdhesionPressurizing force: 5N, Test time: 10±1sec.No remarkable damage or removal of the top in time	Clause 4.24	relative humidity, 1.5hours on and 0.5 hours off	,		
Clause 4.23Control of Vol 2 C, the near of and one of and one of and one of and one of a sector	Load Life(Endurance)	1000 +48/-0 hours; loaded with RCWV or $V_{max}$ in chamber			
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Clause 4.33PCB(FR4), bending once 3mm for 10sec, 5mm for WR04 $\Delta R/R \max. \pm (1\%+0.05\Omega)$ AdhesionPressurizing force: 5N, Test time: $10\pm1sec.$ No remarkable damage or removal of the table is the sec.	Bending strength	Resistors mounted on a 90mm glass epoxy resin		50 0	
	Clause 4.33	PCB(FR4), bending once 3mm for 10sec, 5mm for WR04	ΔR/R max. ±(1%+0.05Ω)		
Clause 4.32 the terminations	Adhesion	Pressurizing force: 5N, Test time: 10±1sec.	No remarkable damage or rer	moval of	
	Clause 4.32		the terminations		

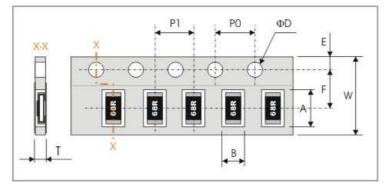


#### **Approval sheet**

TEST PROCEDURE / TEST METHOD	REQUIREMENT		
1231	PROCEDORE/TEST METHOD	Resistor	0Ω
Insulation Resistance	Apply the maximum overload voltage (DC) for 1minute	R≧10GΩ	
JISC5201-1:1998			
Clause 4.6			
Dielectric Withstand	Apply the maximum overload voltage (AC) for 1 minute	No breakdown or flashover	
Voltage			
JISC5201-1:1998			
Clause 4.7			

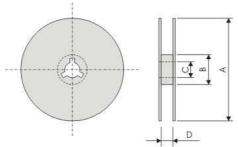
## PACKAGING

Paper Tape specifications (unit :mm)



Series No.	А	В	W	F	E
WF04P	1.20±0.10	0.70±0.10	8.00±0.30	3.50±0.20	1.75±0.10
Series No.	P1	P0	ΦD	Т	
WF04P	2.00±0.10	4.00±0.10	Φ1.50 <sup>+0.1</sup> -0.0	0.40±0.05	

#### 7" Reel dimensions



Symbol	А	В	С	D	
(unit : mm)	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	9.0±0.5	